

CHENZHUO LIEPFL MED 2 2917 • 1015 Lausanne, Switzerland • +41 78 222 48 49 • chenzhuo.li@epfl.ch

EDUCATION

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| École Polytechnique Fédérale de Lausanne | Lausanne, Switzerland |
| Doctoral Student in Solid Mechanics | Present |
| Beihang University | Beijing, China |
| B.S. in Flying Vehicle Power Engineering. GPA: 3.7/4.0 | Jun 2018 |
| Polytechnic University of Milan | Milan, Italy |
| Undergraduate International Exchange Program | Sep 2017 – Feb 2018 |

AWARDS AND HONORS

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|---|-----------|
| • First-Class Academic Scholarship | 2020 |
| • Freshman Merit Scholarship | 2019 |
| • First-Class Academic Scholarship | 2019 |
| • First-Class Academic Scholarship | 2018 |
| • Full Scholarship for Undergraduate Exchange Program (China Scholarship Council) | 2018 |
| • Third Prize for the 26th “Feng Ru Cup” Competition | 2016 |
| • Student Research Training Grant (RMB3500) | 2015-2016 |

PUBLICATIONS

- T Benkley, **C Li***, and JM Kolinski (2023). “Estimation of the Deformation Gradient Tensor by Particle Tracking Near a Free Boundary with Quantified Error.” *Exp Mech* 63:1255-1270
- **C Li***, X Wei*, M Wang, M Adda-Bedia, and JM Kolinski (2023). “Crack tip kinematics reveal the process zone structure in brittle hydrogel fracture.” *J Mech Phys Solids* 178:105330
- K Zhu*, **C Li***, and B Pan (2022). “Rapid and repeatable fluorescent speckle pattern fabrication using a handheld inkjet printer.” *Exp Mech* 62:627-637
- X Zhang*, **C Li***, L Yu, and B Pan (2021). “Heatwave distortion correction using an improved reference sample compensation method and multispectral digital image correlation.” *Appl Opt* 60(13):3716-3723
- B Dong, **C Li**, and B Pan (2021). “Fluorescent 2D digital image correlation with built-in coaxial illumination for deformation measurement in space-constrained scenarios.” *Exp Mech* 61:653-661
- B Fu*, **C Li***, P Ou and B Dong (2020). “Enhanced digital gradient sensing using backlight digital speckle target.” *Sensors* 20(22):6557
- **C Li**, Haojian Luo and B Pan (2020). “High-throughput measurement of coefficient of thermal expansion using a high-resolution digital single-lens reflex camera and digital image correlation.” *Rev Sci Instrum* 91(10):105106
- B Dong*, **C Li***, and B Pan (2020). “Fluorescent digital image correlation applied for macroscale deformation measurement.” *Appl Phys Lett* 117(4):044101
- B Dong*, **C Li***, and B Pan (2019). “Ultrasensitive video extensometer using single-camera dual field-of-view telecentric imaging system.” *Opt Lett* 44(18):4499-4502
- **C Li***, B Dong*, and B Pan (2019). “A flexible and easy-to-implement single-camera microscopic 3D digital image correlation technique.” *Meas Sci Technol* 30(8):085002

(* donates equal contribution)

PRESENTATIONS

- “High-Resolution Quasistatic Near-Crack-Tip Deformation Fields in Brittle Hydrogels.” *11th European Solid Mechanics Conference*, Galway, July 2022
- “New exploration and application of fluorescent digital image correlation.” *International Digital Image Correlation Society Conference*, Virtual, Oct 2020
- “High-throughput CTE determination of bulk materials based on DSLR and DIC.” (in Chinese) *The 26th Annual Conference of Beijing Society of Theoretical and Applied Mechanics*, Beijing, Jan 2020

RESEARCH EXPERIENCE

Institute of Solid Mechanics, Beihang University

Beijing, China

Research Assistant

Oct 2018 – Jan 2021

- Discovered the advantages of fluorescent ink in macroscale digital image correlation and applied it to telecentric imaging with build-in coaxial illumination for deformation measurement in confined space
- Simplified the speckle target in the digital gradient sensing and improved the measurement accuracy
- Designed and executed high-throughput measurement of coefficients of thermal expansion of bulk materials using a digital single lens reflex and digital image correlation
- Developed an ultrasensitive video extensometer based on the idea of field-of-view separation and telecentric imaging
- Developed a single-camera three-dimensional microscopic digital image correlation technique
- Assessed the drift error and distortion between slices obtained by laser scanning confocal microscope (LSCM) using microscale digital image correlation
- Performed digital image correlation on scanning electron microscope images and analyzed the factors affecting the quality of the microscale speckle pattern

Center of Space Exploration (Chongqing University), Ministry of Education

Beijing, China

Experiment Assistant

Jun – Sep 2018

- Assisted with the experiment preparation of the Chang'e-4 Lunar Biosphere Mini-Ecosystem
- Operated the equipment, collected experimental data and monitored the health of the mini-ecosystem
- Performed analysis on the acquired data, deduced the internal status of the mini-ecosystem and conducted troubleshooting when necessary

Institute of Solid Mechanics, Beihang University

Beijing, China

Undergraduate Researcher

Sep 2017 – Jun 2018

- Generated finite element model of 3D closed-cell porous materials with spherical/polyhedral pores using AutoCAD, Rhinoceros and Hypermesh
- Performed finite element analysis using ABAQUS and investigated the effective bulk modulus of porous materials with porosity from 0 to 99%

Student Research Training Program, Beihang University

Beijing, China

Team Leader and APP developer

May 2015 – Oct 2016

- Planned the project schedule and managed the research funding
- Developed a remote-control toy car based on Raspberry Pi and an IOS app, realizing motion control and real-time video streaming

ADDITIONAL EXPERIENCE

Wroclaw University of Science and Technology

Wroclaw, Poland

Summer School in MEMS and Microsystems

Jul 2019

University of Cambridge

Summer School in Nanotechnology and Quantum Technologies

Cambridge, UK

Jul 2017

Peter the Great St. Petersburg Polytechnic University

Summer School in Turbomachinery

St. Petersburg, Russia

Aug 2016

AIESEC International Inc.

International Volunteer in Women Empowerment

Hyderabad, India

Jul – Aug 2015

SKILLS

Computer: MATLAB, Python, 2D/3D Modelling, Finite Element Analysis

Laboratory: Scanning Electron Microscope, Nanoscribe, Raspberry Pi

Languages: Chinese(native), English(proficient)